

*Sub D1* --17. (New) A process for mechanical chemical polishing in the integrated circuits industry, comprising rubbing a layer with a support impregnated with an abrasive composition, wherein

said layer is (1) a material selected from the group consisting of silicon oxide, silicon nitride, and a polymer having a low dielectric constant, or (2) one layer of silicon oxide and another layer of silicon nitride, and

said abrasive composition comprises an aqueous acid suspension of

*C1* (i) individualized colloidal silica particles not linked to each other by siloxane bonds,  
together with (ii) a surfactant.--

Add the following new claims:

--18. (New) The process of claim 17, wherein said surfactant is an anionic or non-ionic surfactant.

--19. (New) The process of claim 18, wherein said surfactant is anionic.

*Sub E2* --20. (New) The process of claim 19, wherein said rubbing is carried out with said composition at pH between 1 and 5, and

said individualized colloidal silica particles have diameters between 12 nm and 100 nm.

--21. (New) The process of claim 18, wherein said rubbing is carried out with said composition at pH between 1 and 5, and

said individualized colloidal silica particles have diameters between 12 nm and 100 nm.

--22. (New) The process of claim 17, wherein said rubbing is carried out with said composition at pH between 1 and 5, and

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said individualized colloidal silica particles have diameters between 12 nm and 100 nm.

--23. (New) The process of claim 22, wherein said pH is between 2 and 3, and

said particle size is between 35 and 50 nm.

--24. (New) The process of claim 21, wherein said pH is between 2 and 3, and

said particle size is between 35 and 50 nm.

--25. (New) The process of claim 20, wherein said pH is between 2 and 3, and

said particle size is between 35 and 50 nm.

--26. (New) The process of claim 25, wherein the concentration by weight of said individualized colloidal silica particles is between 25 and 35 % in said aqueous acid suspension.

--27. (New) The process of claim 24, wherein the concentration by weight of said individualized colloidal silica particles is between 25 and 35 % in said aqueous acid suspension.

*CA* --28. (New) The process of claim 23, wherein the concentration by weight of said individualized colloidal silica particles is between 25 and 35 % in said aqueous acid suspension.

--29. (New) The process of claim 22, wherein the concentration by weight of said individualized colloidal silica particles is between 25 and 35 % in said aqueous acid suspension.

--30. (New) The process of claim 21, wherein the concentration by weight of said individualized colloidal silica particles is between 25 and 35 % in said aqueous acid suspension.

--31. (New) The process of claim 18 wherein the volumetric concentration of said surfactant is between 0.001% and 5%.

--32. (New) The process of claim 20 wherein the volumetric concentration of said surfactant is between 0.001% and 5%.

--33. (New) The process of claim 25 wherein the volumetric concentration of said surfactant is between 0.001% and 5%.

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--34. (New) The process of claim 18, wherein the volumetric concentration of said surfactant is between 0.01% and 1%.

--35. (New) The process of claim 22, wherein the volumetric concentration of said surfactant is between 0.01% and 1%.

--36. (New) The process of claim 26, wherein the volumetric concentration of said surfactant is between 0.01% and 1%.--

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REMARKS

The Official Action of February 14, 2001, Paper No. 5, and the references cited therein have been carefully reviewed. The claims in the application are now claims 17-36, and these claims define patentable subject matter warranting their allowance. Applicants accordingly respectfully request favorable reconsideration and allowance.